

DISCRETE SOCKETS



✓ Active

TE CONNECTIVITY (TE)

SOCKET, MIN-SPR B-N SN-SN SER-2

MINI-SPRING SOCKETS | Series 3

5645952-1

TE Internal Number: 5645952-1

EU RoHS Compliant EU ELV Compliant

Hole Size (Recommended) 1.32 mm [.052 in]

Socket Length 4.67 mm [.184 in]

Sealant Without

Sleeve Style Bullet Nose

Wire/Cable Size $.081 - .326 \, \text{mm}^2 [\, 28 - 22 \, AWG \,]$



PRODUCT DRAWING

English



★ 3D PDF

DOCUMENTATION

Product Drawings

MINIATURE SPRING SOCKET ASSEMBLY SERIES 2 LONG

PDF (TIFF AVAILABLE)

English

CAD Files

Customer View Model

3D_IGS.ZIP

English

Customer View Model

3D_STP.ZIP

English

Customer View Model

2D_DXF.ZIP

English

3D PDF

PDF

English

FEATURES



Please review product documents or contact us for the latest agency approval information.

Please Note: Use the Product Drawing for all design activity.

Product Type Features

Sleeve Style Bullet Nose

Connector System Cable-to-Board

Sealable No

Connector & Contact Terminates To Printed Circuit Board

Product Type Contact

Profile Zero

Wire/Cable Type Discrete Wire

Body Features

Sealant Without

Sleeve Plating Material Tin

Sleeve Material Copper

Contact Features

Contact Current Rating (Max) (A) 5

Contact Type Socket

Contact Spring Plating Material Tin

Contact Mating Area Plating Thickness 30 µm [30 µin]

Contact Transmits (Typical) Signal (Data)/Power

Contact Base Material Beryllium Copper

Socket Type Discrete

Termination Features

Termination Method to PC Board Through Hole - Press-Fit

Termination Method to Wire/Cable Solder

Insertion Method Hand/Semi-Automatic/Automatic

Dimensions

Socket Length 4.67 mm [.184 in]

Hole Size (Recommended) 1.32 mm [.052 in]

Wire/Cable Size .081 - .326 mm² [28 - 22 AWG]

Mating Pin Diameter Range .36 – .66 mm [.014 – .026 in]

PCB Thickness (Recommended) .79 – 3.18 mm [.031 – .125 in]

Usage Conditions

Operating Temperature Range -65 – 125 °C [-85 – 257 °F]

Operation/Application	
Circuit Application Power, Signal	
Packaging Features	
Packaging Method Bag, Loose Piece Packaging Quantity 2000	
Other	
Spring Material Beryllium Copper	
PRODUCT COMPLIANCE	+
Statement of Compliance	
Statement of Compliance PDF	